ABSTRACT

METHOD OF PROCESSING SEMICONDUCTOR WAFER AND SEMICONDUCTOR WAFER SUPPORTING MEMBER

A method of processing a semiconductor wafer, comprising the steps of:

securing a semiconductor wafer on which circuits are formed to a semiconductor wafer supporting member having a data carrier;

inputting information required for semiconductor wafer working in the data carrier; and

reading the information from the data carrier and working the semiconductor wafer in accordance with the read information.

Information required for a process control for semiconductor wafer working is memorized in a data carrier of a semiconductor wafer supporting member, so that the load on a host computer is reduced and, when wafers are transferred between plants, requisite information is transferred together with the wafers to thereby facilitate controlling the information therefor. Moreover, a series of back grinding, dicing and pickup operations can be performed in the same configuration wherein the wafer (chip) is held on the supporting member to thereby facilitate a process control therefor, and the carrying between different operations can be performed in the configuration wherein the wafer is held on the supporting member to thereby enable avoiding wafer breakage during the carrying.